

PATENT APPLICATION

Sheet 1 of 2

FORM PTO-1449 LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)		ATTY. DOCKET NO. 10970792-4	APPLICATION NO.	CONFIRMATION NO.
		APPLICANT Melissa D. Boyd et al.		
		FILING DATE H rewith	GROUP	unkn.

REFERENCE DESIGNATION U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
1A	4,917,286	04/1990	Pollacek	
1B	5,016,023	05/1991	Chan et al.	
1C	5,489,930	02/1996	Anderson	
1D	5,808,635	09/1998	Kneezel et al.	
1E	5,939,206	08/1999	Kneezel et al.	
1F	6,123,410	09/2000	Beerling et al.	
1G	6,322,206	11/2001	Boyd et al.	
1H	5,565,900	10/1996	Cowger et al.	
1I	6,343,857	02/2002	Cowger	
1J	4,380,770	04/1983	Maruyama	
1K	5,087,930	02/1992	Roy et al.	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBLICATION DATE	NAME OF PATENTEE OR APPLICANT	Pages/Columns/Lines Where Relevant Passages/Figures Appear	Check if Translation attached
	1L					
	1M					
	1N					
	1O					
	1P					

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

1Q	'Precision Flip-Chip Solder Bump Interconnects For Optical Packaging'; William R. Imler et al.; December 1992; IEEE; Vol. 15; No. 6; pgs: 977-982.
1R	'Use Of AuSn Solder Bumps In Three-Dimensional Passive Aligned Packaging of LD/PD Arrays On Si Optical Benches'; Masataka Itoh, et al; 1996; IEEE; pgs: 1-7.
1S	'Active Atmosphere Solder Self-Alignment And Bonding Of Optical Components'; R.D. Eshmukh et al.; Vol. 16; No. 2; Second Quarter 1993; International Journal Of Microcircuits And Electronics Packaging; pgs: 97-107.

EXAMINER	DATE CONSIDERED
	9/13/04

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EXAMINER INITIAL	DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
2A	5,097,275	03/1992	Takita	
2B	5,561,448	10/1996	Kaneko et al.	
2C				
2D				
2E				
2F				
2G				
2H				
2I				
2J				
2K				

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	2L					
	2M					
	2N					
	2O					
	2P					

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

2Q	"Multilayered Focal Plane Structures With Self-Aligning Detector Assembly"; David E. Ludwig; SPIE; Vol. 2745; 1996; pgs: 149-158.
2R	"Experimental Results On The Self-Alignment Process Using Au/Sn Metallurgy And On The Growth Of The S-Phase During The Reflow"; Christine Kallmayer, et al; 1995; Semiconductor Technology Center, Inc-Symposium; pgs 225-237.
2S	"Photolithography In Anisotropically Etched Grooves"; S. Linder, et al.; 1996; IEEE; pgs. 38-43.

EXAMINER	DATE CONSIDERED
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